

## Abstract

A heat-radiating structure of chip provides effective heat-radiating paths and also maintains good structural stability to protect chips. A bearing rack is connected beside a flip chip type chip on a circuit substrate. The bearing rack is  
5 connected with a heat-radiating sheet. A projective portion is disposed at the center of the heat-radiating sheet facing the chip. The surfaces of the projective portion and the chip are connected together through adhesive. Several grooves are disposed on the surface of the heat-radiating sheet facing the chip to reduce the weight of the heat-radiating sheet and maintain its structural rigidity. Each  
10 side of the bearing rack is not connected together to avoid regions with a too large local thermal stress. Moreover, heat-spreading paths for hot air are also provided to prevent the heat-radiating sheet from extra stress due to hot expansion and cold shrinkage during baking in the packaging process.